

BluNor BC40C is a powerful, highly flexible, ultra low power Bluetooth Low Energy (BLE) using Nordic nRF5340 SoC. With a dual core ARM Cortex<sup>™</sup> M33 MCU, embedded 2.4GHz multi-protocol transceiver, and an integrated PCB trace antenna or a chip antenna. It allows faster time to market with reduced development cost.

No external component needed to minimize host PCB area: Both 32 MHz and 32.768 KHz, -40°C to +105°C, 20 PPM crystals are integrated. DCDC inductors for VDD and VDDH are integrated.

#### Specifications:

- nRF5340 CLAA, dual core ARM® Cortex M33
- Application Core
  - 128/64 MHz Cortex M33 with FPU and DSP instructions
  - 1MB flash, 512KB RAM
  - 8KB 2-way set associate cache
  - ARM® TrustZone® Cryptocell-312 co-processor
- Network core:
  - 64 MHz Cortex M33 with 2KB instruction cache
  - 256KB flash, 64KB RAM
  - 2.6 mA in RX and 3.2 mA in 0dBm TX
  - Receiver Sensitivity: -98 dBm at 1Mbps
  - TX power: programmable +3dBm to -20dBm
  - BLE 5.1 data rate: 2Mbps, 1Mbps, 500kbps, 125kbps.
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- DC-DC converter, inductors for VDD, VDDH on board.
- Direct powered by Lithium batteries or USB supply (up to 5.5V)
- Serial Wire Debug (SWD)

#### Model Summaries

- Nordic SoftDevice Ready
- Over-the-Air (OTA) firmware update
- 48 General purpose I/O pins
- USB 2.0 full speed (12 Mbps) controller
- QSPI interface
- Type 2 NFC-A tag with wake-on field, Touch-to-pair support
- Programmable peripheral interconnect (PPI)
- 12 bit/200 Ksps ADC, 8 configurable channels with programmable gain
- Temperature sensor
- Up to 3x pulse width modulator (PWM)
- Audio peripherals: I<sup>2</sup>S, digital microphone interface (PDM)
- 5 x 32 bit timers with counter mode
- Up to 3x SPI masters/3x SPI slaves
- Up to 2x I<sup>2</sup>C compatible 2-wire masters/slaves
- 2x UART (CTS/RTS)
- Quadrature Demodulator (QDEC)
- 2x real time counters (RTC)
- LGA pins: 64.
- Both 32 MHz and 32.768KHz crystals on board
- Integrated PCB trace or chip antenna
- Operation voltage: 1.7V to 5.5V
- QDID:

module	BC40C	BC40M	BC40P
SoC	nRF5340 CLAA	nRF5340 CLAA	nRF5340 CLAA
Size	8.4x11.5x1.5 mm	8.4(10.1)x12.7x1.5mm	8.4x9x1.5mm
32 MHz and 32.768 kHz crystals	Integrated	Integrated	Integrated
DC converter inductors, VDD,VDDH	Integrated	Integrated	Integrated
BT Antenna	Chip	PCB trace Note: can only used with the identical trace as approved, and designed in the manual. Modification of the trace requires class II of the antenna changes.	Pads for external
Max TX			
Operating temp.	-40°C to +105°C	-40°C to +105°C	-40°C to +105°C
Availability	Sample 05/2021	Sample 05/2021	Sample 06/2021



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# BLE 5.1, Modules, BC40C, BC40M, BC40P

### 1. Introduction

BluNor BC40C Series are powerful, highly flexible, ultra low power wireless modules using Nordic nRF5340 SoCs. With a dual core ARM Cortex<sup>™</sup> M33 MCU, embedded 2.4GHz multi-protocol transceiver, and an integrated antenna, it allows faster time to market with reduced development cost.

#### **BC40C Block Diagram**

The following is a block diagram of BC40C. Antenna circuit and main clock are integrated. All 48 GPIOs of nRF5340 can be accessed from main board. For lower power consumption at idle state, a 32.768 kHz crystal can be added on the host board.



There are 2 modules in the BC40C Series.

### BC40C

- Uses an nRF5340 CLAA with dual core Cortex M33 MCU
- Integrated chip antenna.
- Size: 8.4x11.5x1.5mm

### BC40M

- Uses an nRF5340 CLAA with dual core Cortex M33 MCU
- Integrated PCB trace antenna.
- Size: 8.4 (10.1)x12.7x1.5mm, L shape.

### BC40P

- Uses an nRF5340 CLAA with dual core Cortex M33 MCU
- Pads for an external antenna.
- Size: 8.4x9.0x1.5mm.





### 2. Codes Development Using Nordic Tools

Development tools from Nordic and other third party development tools recommended by Nordic should be used.

### **Over-The-Air DFU**

The nRF52840 is supported by an Over-The-Air Device Firmware Upgrade (OTA DFU) feature. This allows for in the field updates of application software and SoftDevice.

#### nRF Connect SDK

nRF Connect SDK is a scalable and unified software development kit for building products based on all our nRF52, nRF53 and nRF91 Series wireless devices. It offers developers an extensible framework for building size-optimized software for memory-constrained devices as well as powerful and complex software for more advanced devices and applications. It integrates the Zephyr RTOS and a wide range of samples, application protocols, protocol stacks, libraries and hardware drivers.

For developing Bluetooth Low Energy, Thread and Zigbee products, the nRF Connect SDK contains all needed software, including protocol stacks. For developing cellular IoT products it contains everything except the LTE modem firmware that must be downloaded separately from the nRF9160 SiP product page. See the cellular IoT software for more details.

nRF Connect SDK also offers an unique integration of HomeKit Accessory Development Kit for developing products using both HomeKit over Thread and HomeKit over Bluetooth Low Energy. It is a highly optimized solution that enables battery-powered products with both the HomeKit Accessory Protocol (HAP) and application firmware running on a single chip. MFi licensees can get access to the HomeKit repository by contacting us via Nordic DevZone private ticket.

nRF Connect SDK offers a single code base for all our devices and software components. It simplifies porting modules, libraries and drivers from one application to another, thus reducing development time. By enabling developers to pick and choose the essential software components for their application, high memory efficiency is guaranteed.

nRF Connect SDK is publicly hosted on GitHub, offers source code management with Git and has free SEGGER Embedded Studio IDE support. Nordic runs continuous integration tests on the nRF Connect SDK code to ensure robust and secure production quality code.

### **Development Tools**

Nordic Semiconductor provides a complete range of hardware and software development tools for the nRF53 Series devices. nRF53 DK board is recommended for firmware development.

Nordic software development tools can be downloaded.



### **3. Product Descriptions**

Brief description of nRF5340 SoC is provided. For full description of the SoC, please download from Nordic Semiconductor website.

https://www.nordicsemi.com/eng/Products/Bluetooth-low-energy



#### Block Diagram of nRF5340

The following is a block diagram of Nordic nRF5340 Bluetooth Low Energy (BLE) SoC. Arrows with white



heads indicate signals that share physical pins with other signals.



nRF5340 is a wireless ultra-low power multiple core System on Chip (SoC) integrating two fully programmable Arm Cortex M33 processors, advanced security features, a range of peripherals, and a multi protocol 2.4 GHz transceiver. transceiver supports Bluetooth low energy.

The two Arm Cortex M33 processors share the power, clock, and peripheral architecture with Nordic Semiconductor nRF51, nRF52, and nRF91 Series of PAN/LAN SoCs, ensuring minimal porting efforts. The application core is a full-featured Arm Cortex M33 processor including DSP instructions and FPU and running at up to 128 MHz with 1MB of flash and 512 KB of RAM. The option to run the application processor at 64 MHz allows the CPU to increase energy efficiency. The network core is an Arm Cortex M33 processor with a reduced feature set, designed for ultra-low power operation. It runs at a fixed 64 MHz frequency and contains 256 KB of flash and 64 KB of RAM.

The peripheral set offers a variety of analog and digital functionality enabling single chip implementation of a wide range of applications. Arm trustZone technology, Arm cryptoCell-312, and supporting blocks for ysytem protection and key management are embedded for the advanced security needed for IoT applications.

### **Mechanical Drawings**

Soldering pads are identical for BC40C, BC40M, and BC40P. All modules have 64 LGA (Land Grid Array) pins.

Antenna areas are different. Mechanical drawings are different.

BC40C drawings, top size is BC40C 0.8mm .5 tos mm 0.8mm Ø = 0.3mm 0 0 O 0 0 0 0 EO A0 BO CO DO FO G0 H0 0 0 0 0 0 0 0 -C1 D1 E1 F1 A1 B1 G1 H1 0 0 0 0 0 0 0 0 C2 A2 **B2** D2 E2 F2 G2 H2 O O 0 0 0 0 0 0 A3 **B**3 C3 D3 E3 F3 G3 H3 0 O 0 0 0 Ö 0 0 **B4** D4 A4 E4 F4 G4 H4 0 0 0 0 0 0 0 0 A5 BS C5 D5 E5 F5 G5 HS .97 mm 0 0 0 0 0 0 0 0 CG B6 DG A6 E6 F6 G6 H6 0 0 0. 0 0 0 0 B7 D7 E7 F7 G7 H7 1.16mm 8.4 :85 mm 4

8.4x11.5x1.5mm.



mechanical view. Module



#### BC40M



mechanical drawings, top view. Module size is 8.4 (10.1) x 12.7 x 1.5mm, L-shape.

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#### Pin Assignments of BC40C

The followings are BC40C and BC40M pin assignment. Pin functions are in a table in next section. Please refer to Nordic nRF5340 Product Specifications for detailed descriptions and features supported.



https://infocenter.nordicsemi.com/index.jsp?topic=%2Fstruct\_nrf53%2Fstruct%2Fnrf5340.html&cp=3\_0



BC40P pin assignment is below. It has two additional pins for external antenna connection.



pin#Onlypin#pin nameDescriptions11ANTConnection to an external antenna, BC40P only.2GNDGround for an external antenna.A0H2P109GPIOA1K3P104GPIOA2K5P020GPIO	BC40C/M/P	BC40P nRF5340	BC40C/M/P		
1ANTConnection to an external antenna, BC40P only.2GNDGround for an external antenna.A0H2P109GPIOA1K3P104GPIOA2K5P020GPIO	pin#	Only pin#	pin#	pin name	Descriptions
2GNDGround for an external antenna.A0H2P109GPIOA1K3P104GPIOA2K5P020GPIO		1		ANT	Connection to an external antenna, BC40P only.
A0 H2 P109 GPIO   A1 K3 P104 GPIO   A2 K5 P020 GPIO		2		GND	Ground for an external antenna.
A1 K3 P104 GPIO   A2 K5 P020 GPIO	A0	H2	A0	P109	GPIO
A2 K5 P020 GPIO	A1	K3	A1	P104	GPIO
	A2	K5	A2	P020	GPIO
A3 L7 P017/QSPI_CLK GPIO, Quad Serial Peripheral Interface, clock	A3	L7	A3	P017/QSPI_CLK	GPIO, Quad Serial Peripheral Interface, clock
A4 L9 P015/QSPI2 GPIO, Quad Serial Peripheral Interface, IO2	A4	L9	A4	P015/QSPI2	GPIO, Quad Serial Peripheral Interface, IO2
A5 K10 P013/QSPI0 GPIO, Quad Serial Peripheral Interface, IO0	A5	K10	A5	P013/QSPI0	GPIO, Quad Serial Peripheral Interface, IO0
A6 L3 P105 GPIO	A6	L3	A6	P105	GPIO
A7 J3 P106 GPIO	A7	J3	A7	P106	GPIO
B0 L1 P025/AIN4 GPIO, Analog input	B0	L1	B0	P025/AIN4	GPIO, Analog input
B1 K2 P024 GPIO	B1	K2	B1	P024	GPIO
B2 K4 P022 GPIO	B2	K4	B2	P022	GPIO
B3 K7 P018/QSPI_CS GPIO, Quad Serial Peripheral Interface, chip select	B3	K7	B3	P018/QSPI_CS	GPIO, Quad Serial Peripheral Interface, chip select
B4 K9 P014/QSPI1 GPIO, Quad Serial Peripheral Interface, IO1	B4	K9	B4	P014/QSPI1	GPIO, Quad Serial Peripheral Interface, IO1
B5 K8 P016/QSPI3 GPIO, Quad Serial Peripheral Interface, IO3	B5	K8	B5	P016/QSPI3	GPIO, Quad Serial Peripheral Interface, IO3
B6 J10 P007/AIN3 GPIO, Analog input	B6	J10	B6	P007/AIN3	GPIO, Analog input
B7 J6 P012 GPIO, High speed SPI_DCX	B7	J6	B7	P012	GPIO, High speed SPI_DCX
C0 H1 P027/AIN6 GPIO, Analog input	C0	H1	C0	P027/AIN6	GPIO, Analog input
C1 J2 P026/AIN5 GPIO, Analog input	C1	J2	C1	P026/AIN5	GPIO, Analog input



C3 J5 P019 GPI0   C4 J9 P009 GPI0, High speed SPL MOSI   C5 J11 P102/2C GPI0, IZC interface   C6 H12 P008 GPI0, IXC interface   C7 L12 P008 GPI0, NFC anterna connection   C7 L12 P008 GPI0, NFC anterna connection   D0 F1 SWDIC Serial wire debug clock for debug and programming   D1 F2 SWDICLK Serial wire debug clock for debug and programming   D2 G2 RESET Reset, active low with internal pull up   D3 A5 VSS Ground   D4 F10 P005/AIN1 GPI0, Analog input   D5 G10 P004AIN2 GPI0, Analog input   D6 H3 P023 GPI0   E1 E2 F02 G3   D4 P006/AIN2 GPI0, Analog input   E2 F03 GPI0   E3 GS F03   E4 E10 P10	C2	J4	P021	GPIO
C4 J9 P009 CPIO, Hgh speed SPI_MOSI   C5 J11 P102/I2C GPIO, I2C interface   C6 H12 P003NFC2 GPIO, NFC antenna connection   C7 L12 P008 GPIO, NFC antenna connection   C7 L12 P008 GPIO, NFC antenna connection   D0 F1 SWDIO Serial wire debug dat for debug and programming   D1 F2 SWDICLK Serial wire debug dat for debug and programming   D2 G2 ////////////////////////////////////	C3	J5	P019	GPIO
C5 J11 P102/2C GPI0, I2C interface   C6 H12 P003/IFC2 GPI0, IIgh speed SPI clock   C7 L12 P008 GPI0, High speed SPI clock   D0 F1 SWDI0 Serial wire debug clock for debug and programming   D1 F2 SWDICK Serial wire debug clock for debug and programming   D2 G2 ////RESET Reset, active low with internal pull up   D3 A5 VSS Ground   D4 F10 P005/AIN1 GPI0, Analog input   D5 G10 P004/AIN0 GPI0, Analog input   D6 H3 P023 GPI0   D7 H10 P006/AIN2 GPI0, Analog input   D6 A5 GND Ground   E1 E2 P029 GPI0   E3 C5 P014 GPI0, I2C interface   E7 J7 P011 GPI0, I2C interface   F7 J7 P011 GPI0, I2C interface   F7 J7 P014 GPI	C4	J9	P009	GPIO, High speed SPI_MOSI
C6 H12 P003/NFC2 CPI0, NFC antenna connection   C7 L12 P008 GPI0, High speed SPI clock   D0 F1 SWDIO Serial wire debug data for debug and programming   D1 F2 SWDIO Serial wire debug data for debug and programming   D2 G2 //RESET Reset, active low with internal pull up   D3 A5 VSS Ground   D4 F10 P005/AIN0 GPI0, Analog input   D5 G10 P004/AIN0 GPI0, Analog input   D6 H3 P023 GPI0   D7 H10 P006/AIN2 GPI0, Analog input   E1 E2 P029 GPI0   E3 C5 P031 GPI0   E4 E10 P101 GPI0   E4 E10 P101 GPI0, L2 interface   E7 J7 P011 GPI0, L2 interface   E7 J7 P011 GPI0, L2 interface   E7 G7 P112 GPI0, L2 interface	C5	J11	P102/I2C	GPIO, I2C interface
C7 L12 P008 GPIO, High speed SPI clock   D0 F1 SVDIO Serial wire debug data for debug and programming   D1 F2 SWDCLK Serial wire debug dock for debug and programming   D2 G2 /RESET Reset, active low with internal pull up   D3 A5 VSS Ground   D4 F10 P005/AIN1 GPIO, Analog input   D6 H3 P023 GPIO   D6 H3 P023 GPIO   D7 H10 P008/AIN2 GPIO, Analog input   E0 A5 GND Ground   E1 E2 P029 GPIO   E2 G3 P107 GPIO   E3 C5 P031 GPIO   E4 E10 P101 GPIO   E5 D10 P103/RC GPIO, Lic Interface   E7 J7 P011 GPIO, Analog input   F1 E3 P02/AIN7 GPIO, Analog input   F2 F3	C6	H12	P003/NFC2	GPIO, NFC antenna connection
D0 F1 SWD0 Serial wire debug data for debug and programming   D1 F2 SWDCLK Serial wire debug dock for debug and programming   D2 G2 //RESET Reset, active low with internal pull up   D3 A5 VSS Ground   D4 F10 P005/AIN1 GPI0, Analog input   D5 G10 P005/AIN2 GPI0, Analog input   D6 H3 P023 GPI0   D7 H10 P006/AIN2 GPI0, Analog input   E0 A5 GND Ground   E1 E2 P029 GPI0   E3 G5 P031 GPI0   E3 C5 P031 GPI0   E4 E10 P101 GPI0   E5 D10 P103 Ground   F1 E3 P023/AIN7 GPI0, Analog input   F2 F3 P108 GPI0   F3 G7 P112 GPI0   F4 A5 GND <t< td=""><td>C7</td><td>L12</td><td>P008</td><td>GPIO, High speed SPI clock</td></t<>	C7	L12	P008	GPIO, High speed SPI clock
D1F2SWDCLKSerial wire debug clock for debug and programmingD2G2//RESETRest, active low with internal pull upD3A5VSSGroundD4F10P005/AIN1GPIO, Analog inputD5G10P004/AIN0GPIO, Analog inputD6H3P023GPIOD7H10P006/AIN2GPIO, Analog inputE0A5GNDGroundE1E2G3P107E2G3P107GPIOE3C5P031GPIOE4E10P100GPIOE5D10P101GPIOE6K12P103/I2CGPIO Analog inputE6A5.GNDGroundE7J.7P011GPIO, High speed SPI chip selectF7G.7P103/I2CGPIOF8G.7P112GPIOF1E3P029/AIN7GPIOF4A5.GNDGroundF4S1.VDBGPIOF4S1.VDBGPIOF4S1.VDBGPIOF4S1.VDBGPIOF4G11P02/NFC1GPIOG11P02/NFC1GPIOG2E4P10GPIOG3C3VDDCover supply, 1.7V to 3.6VG4B10VDDCover supply, 1.7V to 3.6VG4B10VDCover supply, 1.7V to 3.6VG5J.8P01GFIO<	D0	F1	SWDIO	Serial wire debug data for debug and programming
D2 G2 /RESET Reset, active low with internal pull up   D3 A5 VSS Ground   D4 F10 P005/AIN1 GPIO, Analog input   D5 G10 P004/AIN0 GPIO, Analog input   D6 H30 P0033 GPIO   D7 H10 P006/AIN2 GPIO, Analog input   E0 A5 GND Ground   E1 E2 P029 GPIO   E3 GS P031 GPIO   E4 E10 P101 GPIO   E5 D10 P100 GPIO   E6 K12 P103/I2C GPIO, Izinterface   E7 J7 P011 GPIO, High speed SPI chip select   F0 A5 GND Ground   F1 E3 P028/AIN7 GPIO, Analog input   F2 F3 P108 GPIO   F3 C7 P112 GPIO   F4 A5 GND Ground <td< td=""><td>D1</td><td>F2</td><td>SWDCLK</td><td>Serial wire debug clock for debug and programming</td></td<>	D1	F2	SWDCLK	Serial wire debug clock for debug and programming
D3 A5 VSS Ground   D4 F10 P005/AIN1 GPIO, Analog input   D5 G10 P004/AIN0 GPIO, Analog input   D6 H3 P023 GPIO   D6 H3 P023 GPIO   D7 H10 P006/AIN2 GPIO, Analog input   E0 A5 GND Ground   E1 E2 P029 GPIO   E3 G5 P031 GPIO   E4 E10 P101 GPIO   E5 D10 P100 GPIO   E6 K12 P103/I2C GPIO, I2C Interface   E7 J7 P011 GPIO, Analog input   F1 E3 P028/AIN7 GPIO, Analog input   F2 J7 P011 GPIO, Analog input   F2 A5 GND Ground   F1 E3 P028/AIN7 GPIO, Analog input   F2 B11 VBUS SV input for USB 3.3V regulator	D2	G2	/RESET	Reset, active low with internal pull up
D4 F10 P005/AIN1 GPI0, Analog input   D5 G10 P004/AIN0 GPI0, Analog input   D6 H3 P023 GPI0   D7 H10 P006/AIN2 GPI0, Analog input   D7 H10 P006/AIN2 GPI0, Analog input   E0 A5 GND Ground   E1 E2 P029 GPI0   E3 G.S. P031 GPI0   E3 C.S. P031 GPI0   E4 E10 P101 GPI0   E5 D10 P103 GPI0   E6 K12 P103/I2C GPI0, High speed SPI chip select   F7 J7 P011 GPI0, Analog input   F1 E3 P028/AIN7 GPI0, Analog input   F2 J7 P011 GPI0, Analog input   F3 C7 P112 GPI0   F4 A5 GND Ground   F5 B11 VBUS SV input for USB 3.3V regulator	D3	A5	VSS	Ground
D5 G10 P004/AIN0 GPI0, Analog input   D6 H3 P023 GPI0   D7 H10 P006/AIN2 GPI0, Analog input   E0 A5 GND Ground   E1 E2 P029 GPI0   E2 G3 P107 GPI0   E3 C5 P031 GPI0   E4 E10 P101 GPI0   E4 E10 P101 GPI0   E6 D10 P103/I2C GPI0, I2C interface   E7 J7 P011 GPI0, Analog input   F1 E3 P028/AIN7 GPI0, Analog input   F2 J7 P013/I2C GPI0, Analog input   F2 F3 GND Ground   F4 A5 GND Ground   F3 C7 P112 GPI0   F4 A5 GND Ground   F6 B12 VDH High voltage DC power supply, 2.5V to 5.5V   F7	D4	F10	P005/AIN1	GPIO, Analog input
D6 H3 P023 GPIO   D7 H10 P006/AIN2 GPIO, Analog input   E0 A5 GND Ground   E1 E2 P029 GPIO   E2 G3 P107 GPIO   E3 C5 P031 GPIO   E4 E10 P101 GPIO   E4 E10 P101 GPIO   E5 D10 P100 GPIO   E6 K12 P103/I2C GPIO, Literface   E7 J7 P011 GPIO, Analog input   F0 A5 GND Ground   F1 E3 P028/AIN7 GPIO, Analog input   F2 F3 P108 GPIO   F3 C7 P112 GPIO   F4 A5 GND Ground   F5 B11 VBUS SV input for USB 3.3V regulator   F6 B12 VDDH High voltage DC power supply, 2.5V to 5.5V   F7 G11 <td>D5</td> <td>G10</td> <td>P004/AIN0</td> <td>GPIO, Analog input</td>	D5	G10	P004/AIN0	GPIO, Analog input
D7 H10 P006/AIN2 GPIO, Analog input   E0 A5 GND Ground   E1 E2 P029 GPIO   E2 G3 P107 GPIO   E3 C5 P031 GPIO   E3 C5 P031 GPIO   E4 E10 P101 GPIO   E5 D10 P100 GPIO   E6 K12 P103/I2C GPIO, I2C interface   E7 J7 P011 GPIO, Analog input   F0 A5 GND Ground   F1 E3 P028/AIN7 GPIO, Analog input   F2 F3 P108 GPIO   F3 C7 P112 GPIO   F4 A5 GND Ground   F5 B11 VBUS SV input for USB 3.3V regulator   F6 B12 VDDH High voltage DC power supply, 2.5V to 5.5V   F7 G11 P002/NFC1 GPIO   G14 <	D6	H3	P023	GPIO
E0A5GNDGroundE1E2P029GPIOE2G3P107GPIOE3C5P031GPIOE4E10P101GPIOE5D10P100GPIOE6J7P011GPIO, Lic InterfaceE7J7P011GPIO, Analog inputF1E3P028/AIN7GPIO, Analog inputF2F3P108GPIOF3P112GPIOF4A5GNDGroundF5B11VBUSSV input for USB 3.3V regulatorF6B12VDDHHigh voltage DC power supply, 2.5V to 5.5VF7G11P002/NFC1GPIOG3C8P113GPIOG44B10VDDDC power supply, 1.7V to 3.6VG55A11D-USB dataG66M1D.NC connectG7J8P100GPIO, Nigh speed SPI MISOH1K14S45GND	D7	H10	P006/AIN2	GPIO, Analog input
E1E2P029GPIOE2G3P107GPIOE3C5P031GPIOE4E10P101GPIOE5D10P100GPIOE6K12P103/I2CGPIO, I2C interfaceE7J7P011GPIO, High speed SPI chip selectF0A5GNDGroundF1E3P028/AIN7GPIO, Analog inputF2F3P108GPIOF3C7P112GPIOF4A5GNDGroundF5B11VBUSSV input for USB 3.3V regulatorF6B12VDDHHigh voltage DC power supply, 2.5V to 5.5VF7G11P002/NFC1GPIOG14C4P030GPIOG24E4P110GPIOG35C8P113GPIOG4B10VDDDC power supply, 1.7V to 3.6VG5A11D-USB dataG6NCNC connectG7J8P101GPIOG4A5GNDGroundG4A5GNDGPIONG4B10VDDDC power supply, 1.7V to 3.6VG5A11D-USB dataG6MNCNo connectG7J8P101GPIO, high speed SPI MISOH0A5GNDGroundH1H1A5GNDGroundGroundGround	E0	A5	GND	Ground
E2 G3 P107 GPIO   E3 C5 P031 GPIO   E4 E10 P101 GPIO   E5 D10 P100 GPIO   E6 K12 P103/I2C GPIO, I2C interface   E7 J7 P011 GPIO, I2C interface   F7 J7 P011 GPIO, Analog input   F1 E3 P028/AIN7 GPIO, Analog input   F2 F3 P108 GPIO   F3 P108 GPIO   F4 A5 GND Ground   F3 C7 P112 GPIO   F4 A5 GND Ground   F5 B11 VBUS SV input for USB 3.3V regulator   F6 B12 VDDH High voltage DC power supply, 2.5V to 5.5V   F7 G11 P002/NFC1 GPIO, NFC antenna connection   G14 A5 VSS Ground   G15 A5 VSS Ground   G14	E1	E2	P029	GPIO
E3C5P031GPIOE4E10P101GPIOE5D10P100GPIOE6K12P103/I2CGPIO, I2C interfaceE7J7P011GPIO, High speed SPI chip selectF0A5GNDGroundF1E3P028/IN7GPIO, Analog inputF2F3P108GPIOF4A5GNDGroundF5B11VBUSSV input for USB 3.3V regulatorF6B12VDDHHigh voltage DC power supply, 2.5V to 5.5VF7G11P002/NFC1GPIOG3C4P303GPIOG4B10VDDGPIOG3C8P113GPIOG4B10VDDDC power supply, 1.7V to 3.6VG5A11D-USB dataG6J3SPIOSIS dataG6J3SPIOGPIO, high speed SPI MISOG4B10VDDCC power supply, 1.7V to 3.6VG5A11D-USB dataG6J3SPIOGPIO, high speed SPI MISOHiJ5SMDGround	E2	G3	P107	GPIO
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F7G11P002/NFC1GPIO, NFC antenna connectionG0A5VSSGroundG1C4P030GPIOG2E4P110GPIOG3C8P113GPIOG4B10VDDDC power supply, 1.7V to 3.6VG5A11D-USB dataG6INCNo ConnectG7J8P010GPIO, high speed SPI MISOH1A5GNDGround	F6	B12	VDDH	High voltage DC power supply, 2.5V to 5.5V
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G7 J8 P010 GPI0, high speed SPI MISO   H0 A5 GND Ground   H1 A5 GND Ground	G6		NC	No Connect
H0 A5 GND Ground   H1 A5 GND Ground	G7	J8	P010	GPIO, high speed SPI MISO
H1 A5 GND Ground	H0	A5	GND	Ground
	H1	A5	GND	Ground



H2	C6	P111	GPIO
H3	C9	P114	GPIO
H4	C10	P115	GPIO
H5	A12	D+	USB data
H6		NC	No Connect
H7	A5	VSS	Ground

### **Pin Function**



### Mounting BC40M and BC40C on the Host PCB

The following figure shows recommended mounting of BC40M module on the host PCB.

- For the best Bluetooth range performance, the antenna area of module shall extend 4.4 mm outside the edge of host PCB board, or 4.4 mm outside the edge of a ground plane.
- The next choice is to place a module on a corner of host PCB, the antenna area shall extend 4.4 mm from the edge of ground plane. Ground plane shall be at least 5 mm from the edge of the antenna area of module.
- We don't recommend mounting BC40M module in the middle of a host PCB.



following figure shows recommended mounting of BC40C module on the host PCB.

- For the best Bluetooth range performance, the antenna area of module shall extend 3.2 mm outside the edge of host PCB board, or 3.2 mm outside the edge of a ground plane.
- The next choice is to place a module on a corner of host PCB, the antenna area shall extend 3.2 mm from the edge of ground plane. Ground plane shall be at least 5 mm from the edge of the antenna area of module.
- We don't recommend mounting BC40C module in the middle of a host PCB.

BC40P shall be mounted near the external connector for an antenna.

For the best Bluetooth range performance, keep all external metal at least 30mm from the antenna area.



#### Host Board Design for Low Cost or Long Range

On nRF53 series SoCs, Nordic offers various memory options and protocol supports. Fanstel offers various antenna and power amplifier options. A host board can be designed to accommodate these nRF53 modules. Our suggestions for host PCB design:

If your main goal is minimum PCB cost,

- use a 2-sided PCB.
- Use library component from EV-BC40C Gerber files. They can be downloaded from <a href="http://www.fanstel.com/download-document/">http://www.fanstel.com/download-document/</a>. BC40C library component can be used. However, signal routing can be difficult on a 2-sided PCB.

If you main goal is maximum wireless range,

- use a 4 or more layers PCB.
- Use library component from EV-C40C Gerber files. They can be downloaded from <a href="http://www.fanstel.com/download-document/">http://www.fanstel.com/download-document/</a>.





### 4. BC40C Evaluation Board

An evaluation board consists of the followings:

- Mini USB cable
- Evaluation board
- 10-conductor cable for connection to Nordic nRF53 DK (DK is not included)





#### **EV-BC40C and EV-BC40M Evaluation Board Schematics**

BC40C and evaluation board schematics can be the EV-BC40P schematics on the





#### **EV-BC40P Evaluation Board Schematics**

BC40P module has two additional pins for an external antenna. They are connected to an u.FL connector on the evaluation board.





#### Nordic Development Tools

A Nordic nRF53 DK is recommended for programming this evaluation board. Nordic development tools can be downloaded from:

https://infocenter.nordicsemi.com/index.jsp?topic=%2Fstruct\_nrf53%2Fstruct%2Fnrf5340.html

Many application examples can be downloaded from Nordic website.

Some firmware, Android OS, and iOS app codes can be downloaded from **Bluetooth 5 Codes section** of this Fanstel webpage.

http://www.fanstel.com/download-document/

*BC40* firmware can be used in all nRF5340 modules without power amplifier, e.g., BC40C, BC40M, and BC40P.

#### Android OS Apps

The following Android OS apps are available for download from Google Play Store: **BlueNor nrf5x**: to use with Bluetooth 5 stacks, AT commands, or Slave firmware. Master firmware does not connect to a smartphone. Source codes can be downloaded from http://www.fanstel.com/download-document/

**BlueNor Mesh**: to use with BlueNor mesh firmware to send command to any node in a mesh. Node number is displayed when acknowledgement is received. Source codes will be uploaded to Fanstel website when supporting Bluetooth 5.

### iOS Apps

The following iOS apps can be downloaded from Apple APP Store.

**BlueNor Mesh**: to use with BlueNor mesh firmware to send command to any node in a mesh. Node number is displayed when acknowledgement is received.

BlueNor nrf5x firmware, apps, and source codes will be uploaded when ready.



### **EV-BC40C** EvaluationBoard Schematics

Evaluation board schematics and Gerber files can be downloaded from

#### http://www.fanstel.com/download-document/

Evaluation board can be used as a reference design for using modules. EV-BC40C is designed for the BC40C soldering pads with 64 pins. This EV board can also be used for BC40M and BC40P modules. An external antenna required but not included in EV-BC40P.

#### **Suggestion for Battery Power Application**

Standby current consumption is important for battery-powered product. To reduce host board area, the followings are embedded in modules:

- 32 MHz, 20PPM main crystal and load capacitors.
- 32.768 KHz, 20PPM sleep crystal and load capacitors.
- Inductors and capacitors required for VDD power supply DC to DC converter.
- Inductors and capacitors required for VDDH power supply DC to DC converter.

The external sleep crystal shall be used to have a precise sleep clock frequency. DCDC converter shall be enabled to reduce power consumption.



### 5. Miscellaneous

#### Soldering Temperature-Time Profile for Re-Flow Soldering

Maximum number of cycles for re-flow is 2. No opposite side re-flow is allowed due to module weight.



### Cautions, Design Notes, and Installation Notes

Failure to follow the guidelines set forth in this document may result in degrading of the product's functions and damage to the product.

#### Design Notes

- (1) Follow the conditions written in this specification, especially the control signals of this module.
- (2) The supply voltage has to be free of AC ripple voltage (for example from a battery or a low noise regulator output). For noisy supply voltages, provide a decoupling circuit (for example a ferrite in series connection and a bypass capacitor to ground of at least 47uF directly at the module).
- (3) This product should not be mechanically stressed when installed.
- (4)Keep this product away from heat. Heat is the major cause of decreasing the life of these products.
- (5) Avoid assembly and use of the target equipment in conditions where the products' temperature may exceed the maximum tolerance.
- (6)The supply voltage should not be exceedingly high or reversed. It should not carry noise and/or spikes.



(7) this product away from other high frequency circuits.

#### Notes on Antenna and PCB Layout

(1)Don't use a module with internal antenna inside a metal case.

(2) For PCB layout:

- Avoid running any signal line below module whenever possible,
- No ground plane below antenna,
- If possible, cut-off the portion of main board PCB below antenna.

#### Installation Notes

- (1)Reflow soldering is possible twice based on the time-temperature profile in this data sheets. Set up the temperature at the soldering portion of this product according to this reflow profile.
- (2)Carefully position the products so that their heat will not burn into printed circuit boards or affect the other components that are susceptible to heat.
- (3)Carefully locate these products so that their temperatures will not increase due to the effects of heat generated by neighboring components.
- (4) If a vinyl-covered wire comes into contact with the products, then the cover will melt and generate toxic gas, damaging the insulation. Never allow contact between the cover and these products to occur.
- (5) This product should not be mechanically stressed or vibrated when reflowed.
- (6) If you want to repair your board by hand soldering, please keep the conditions of this chapter.
- (7) Do not wash this product.
- (8)Refer to the recommended pattern when designing a board.
- (9)Pressing on parts of the metal cover or fastening objects to the metal will cause damage to the unit.

#### **Usage Condition Notes**

- (1)Take measures to protect the unit against static electricity. If pulses or other transient loads (a large load applied in a short time) are applied to the products, check and evaluate their operation before assembly on the final products.
- (2)Do not use dropped products.
- (3)Do not touch, damage or soil the pins.
- (4) Follow the recommended condition ratings about the power supply applied to this product.
- (5)Electrode peeling strength: Do not add pressure of more than 4.9N when soldered on PCB
- (6) Pressing on parts of the metal cover or fastening objects to the metal cover will cause damage.



(7) These products are intended for general purpose and standard use in general electronic equipment, such as home appliances, office equipment, information and communication equipment.

#### Storage Notes

(1)The module should not be stressed mechanically during storage.

(2)Do not store these products in the following conditions or the performance characteristics of the product, such as RF performance will be adversely affected:

- Storage in salty air or in an environment with a high concentration of corrosive gas.
- Storage in direct sunlight
- Storage in an environment where the temperature may be outside the range specified.
- Storage of the products for more than one year after the date of delivery storage period.
- (3) Keep this product away from water, poisonous gas and corrosive gas.
- (4) This product should not be stressed or shocked when transported.
- (5) Follow the specification when stacking packed crates (max. 10).

#### Safety Conditions

These specifications are intended to preserve the quality assurance of products and individual components. Before use, check and evaluate the operation when mounted on your products. Abide by these specifications, without deviation when using the products. These products may short-circuit. If electrical shocks, smoke, fire, and/or accidents involving human life are anticipated when a short circuit occurs, then provide the following failsafe functions, as a minimum.

(1)Ensure the safety of the whole system by installing a protection circuit and a protection device.

(2)Ensure the safety of the whole system by installing a redundant circuit or another system to prevent a dual fault causing an unsafe status.

#### **Other Cautions**

- (1)This specification sheet is copyrighted. Reproduction of this data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices.
- (2)Do not use the products for other purposes than those listed.
- (3)Be sure to provide an appropriate failsafe function on your product to prevent an additional damage that may be caused by the abnormal function or the failure of the product.
- (4)This product has been manufactured without any ozone chemical controlled under the Montreal Protocol.
- (5)These products are not intended for other uses, other than under the special conditions shown below. Before using these products under such special conditions, check their performance and



reliability under the said special conditions carefully to determine whether or not they can be used in such a manner.

- In liquid, such as water, salt water, oil, alkali, or organic solvent, or in places where liquid may splash.
- In direct sunlight, outdoors, or in a dusty environment
- In an environment where condensation occurs.
- In an environment with a high concentration of harmful gas.
- (6) If an abnormal voltage is applied due to a problem occurring in other components or circuits, replace these products with new products because they may not be able to provide normal performance even if their electronic characteristics and appearances appear satisfactory.
- (7) When you have any question or uncertainty, contact Fanstel.



#### Packaging and Lot Number

Production modules are delivered in reel, 1000 modules in each reel. Lot number for modules made after May 2019, can be used to track silicon version of SoC, module PCB version, and production test



# Lot: DO V2 18B - 00 00 000

D0: 2 digits, version number of SoC. V2: 2 digits, version number of module PCB. 18B: the first 2 digits for production test codes released year and the last digit for month in hex format. A=October, B=November, C=December. 18B was released in November 2018.

00 00 000, 7 digits, reserved for 2nd SoC for modules with 2 SoCs.

code version.

### FCC LABEL

The Original Equipment Manufacturer (OEM) must ensure that the OEM modular transmitter must be labeled with its own FCC ID number. This includes a clearly visible label on the outside of the final product enclosure that displays the contents shown below. If the FCC ID is not visible when the equipment is installed inside another device, then the outside of the device into which the equipment is installed must also display a label referring to the enclosed equipment

The end product with this module may subject to perform FCC part 15 unintentional emission test requirement and be properly authorized.

This device is intended for OEM integrator only.



### ÉTIQUETTE CI

Le fabricant d'équipement d'origine (OEM) doit s'assurer que le transmetteur modulaire OEM doit être étiqueté avec son propre numéro IC. Cela comprend une étiquette clairement visible à l'extérieur de l'enceinte du produit final qui affiche le contenu indiqué ci-dessous. Si le CI n'est pas visible lorsque l'équipement est installé à l'intérieur d'un autre appareil, l'extérieur de l'appareil dans lequel l'équipement est installé doit également afficher une étiquette faisant référence à l'équipement fourni. Le produit final avec ce module peut être soumis à l'exigence de test d'émission non intentionnelle ISDE et être dûment autorisé. Cet appareil est destiné uniquement aux intégrateurs OEM.

### **Revision History**

- April 2021, Ver. 0.80: Initial draft release
- May 2021, Ver. 0.90: Draft



### Contact Us

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Federal Communications Commission (FCC) Statement



You are cautioned that changes or modifications not expressly approved by the part responsible for compliance could void the user's authority to operate the equipment.

This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- -Reorient or relocate the receiving antenna.
- -Increase the separation between the equipment and receiver.
- (1)-Connect the equipment into an outlet on a circuit different from that to which the receiver is connected. -Consult the dealer or an experienced radio/TV technician for help.

This device complies with Part 15 of the FCC Rules. Operation is subject to the following two conditions:

1) this device may not cause harmful interference, and

2) this device must accept any interference received, including interference that may cause undesired operation of the device.

#### FCC RF Radiation Exposure Statement:

This equipment complies with FCC radiation exposure limits set forth for an uncontrolled environment. End users must follow the specific operating instructions for satisfying RF exposure compliance. This transmitter must not be co-located or operating in conjunction with any other antenna or transmitter.



#### Industry Canada (IC) Statement

This device complies with Industry Canada license-exempt RSS standard(s). Operation is subject to the following two conditions: (1) this device may not cause interference, and (2) this device must accept any interference, including interference that may cause undesired operation of the device.

#### Canada, avis d'Industry Canada (IC)

Le présent appareil est conforme aux CNR d'Industrie Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes:

(1) l'appareil ne doit pas produire de brouillage, et

(2) l'utilisateur de l'appareil doit accepter tout brouillage radioélectrique subi, même si le

brouillage est susceptible d'en compromettre le fonctionnement.

**Note: The end product shall has the words "Contains Transmitter Module** FCC ID: X8WBC40, contient IC: 4100A-BC40"



Information for the OEM and Integrators

The following statement must be included with all versions of this document supplied to an OEM or integrator,

but should not be distributed to the end user.

(1) This device is intended for OEM integrators only.

(2) Please see the full Grant of Equipment document for other restrictions.

BC40C: Chip Antenna, 1 dBi BC40M: PCB trace Antenna, 1.53 dBi; BC40P: Pads for external Antenna, 0.54dBi

Must use the device only in host devices that meet the FCC/ISED RF exposure category of mobile, which means the device is installed and used at distances of at least 20cm from persons.

The end user manual shall include FCC Part 15 /ISED RSS GEN compliance statements related to the transmitter as show in this manual.

Host manufacturer is responsible for compliance of the host system with module installed with all other applicable requirements for the system such as Part 15 B, ICES 003.

Host manufacturer is strongly recommended to confirm compliance with FCC/ISED requirements for the transmitter when the module is installed in the host.

Must have on the host device a label showing Contains FCC ID: X8WBC40, contient IC: 4100A-BC40 The use condition limitations extend to professional users, then instructions must state that this information also extends to the host manufacturer's instruction manual.

This module is stand-alone modular. If the end product will involve the Multiple simultaneously transmitting condition or different operational conditions for a stand-alone modular transmitter in a host, host manufacturer have to consult with module manufacturer for the installation method in end system.

l'hôte doit utiliser l'instrument uniquement dans des dispositifs qui répondent à la fcc / (catégorie d'exposition rf mobile, ce qui signifie le dispositif est installé et utilisé à une distance d'au moins 20 cm de personnes. le manuel de l'utilisateur final doit inclure la partie 15 / (fac rss gen déclarations de conformité relatives à l'émetteur que de montrer dans ce manuel.

le fabricant est responsable de la conformité de l'hôte, le système d'accueil avec le module installé avec toutes les autres exigences applicables du système comme la partie 15 b, ices - 003.

accueillir le fabricant est fortement recommandé de confirmer la conformité avec les exigences de la fcc / (émetteur lorsque le module est installé dans l'hôte. le dispositif d'accueil doivent avoir une étiquette indiquant contient FCC ID: X8WBC40, contient IC: 4100A-BC40

The installation to host depends on the platform of the usage, and may requires further evaluation related to RF exposure.